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**Salamy et al.**

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[54] **USE OF PARTICULAR MIXTURES OF ETHYL LACTATE AND METHYL ETHYL KETONE TO REMOVE UNDESIRABLE PERIPHERAL MATERIAL (E.G. EDGE BEADS) FROM PHOTORESIST-COATED SUBSTRATES**

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**Related U.S. Application Data**

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[51] **Int. Cl.<sup>5</sup>** ..... B01F 1/00

[52] **U.S. Cl.** ..... 252/364; 524/317; 524/364; 430/331

[58] **Field of Search** ..... 524/317, 364; 252/364; 430/331

[56] **References Cited**

**U.S. PATENT DOCUMENTS**

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[57] **ABSTRACT**

A process for removing unwanted photoresist material from the peripheral areas of a photoresist substrate comprising the steps of:

(a) spin coating a photoresist solution onto a surface of a substrate, thereby applying a photoresist coating which comprises a uniform film over substantially all of said substrate surface except for unwanted photoresist material deposits at the peripheral areas of said surface;

(b) contacting said peripheral area of the coated substrate with a sufficient amount of a solvent mixture comprising a mixture of ethyl lactate and methyl ethyl ketone present in a volume ratio of about 65:35 to about 25:75, respectively, to selectively dissolve said unwanted deposits without adversely affecting said uniform film; and

(c) separating said dissolved deposits from said coated substrate.

**3 Claims, No Drawings**